



05/02/2006

**RELIABILITY MONITOR REPORT
FOR**

TO Package

Dallas Semiconductor

**4401 South Beltwood Parkway
Dallas, TX 75244-3292**

**This Report was prepared by
Dallas Semiconductor Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE			
Carsem	3	TO220	Carsem	2	TO92
Carsem	3	TO92	Carsem	2	TO92 (Pb-Free)
Carsem	3	TO92 (Pb-Free)	CIRTEK	2	TO92
CIRTEK	3	TO92	CIRTEK	3	TO92 (Pb-Free)
Hana	3	PR35 (Pb-Free) (TO226)	Hana	3	TO226 (PR35)
Hana	2	TO92	Hana	3	TO92
Hana	2	TO92 (Pb-Free)	Hana	3	TO92 (Pb-Free)

Note: Due to the nature of the construction on this assembly, there is no operating life data collected

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 04/01/2005 and 03/31/2006 .

Assembly Information:

Package Type: PR35 185
Flammability: UL 94-V0
Moisture Sensitivity Level 1
(JEDEC J-STD20A)
Date Code Range: 0529 to 0529

PACKAGE TESTS

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
SOLDERABILITY (Sn/Pb)	0529	DS2434	JESD22-B102, COND C		6	0	
				Total:		0	